

In the claims:

1. (Currently Amended) An apparatus, comprising:  
a plurality of bond pads configured in an array;  
a first plurality of driver cells located ~~nearer to a nearest die edge than~~ between a nearest die edge and the plurality of bond pads; and  
a second plurality of driver cells located farther from the nearest die edge than the plurality of bond pads.
2. (Original) The apparatus of claim 1, wherein the plurality of bond pads are configured in a staggered array.
3. (Previously Amended) The apparatus of claim 2, further comprising a plurality of pre-drive cells located farther from the nearest die edge than the second plurality of driver cells.
4. (Original) The apparatus of claim 3, wherein the plurality of bond pads are configured in a staggered array including an inner ring and an outer ring of bond pads.
5. (Original) The apparatus of claim 4, further comprising a plurality of metal connections, each of the plurality of metal connections to couple one of the first and second pluralities of driver cells to one of the plurality of bond pads.
6. (Original) The apparatus of claim 5, further comprising a plurality of conductive interconnects, each of the plurality of pre-driver cells coupled to one of the first and second pluralities of driver cells by at least one of the plurality of conductive interconnects.

7. (Currently Amended) The apparatus of claim 6, wherein each of the plurality of conductive interconnects substantially more narrow in width than each of the plurality of metal connections.

8. (Currently Amended) The apparatus of claim 7, wherein the first and second pluralities of driver cells each ~~having~~ have a width of approximately 80 microns.

9. Cancelled

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